PRODUCT SPECIFICATIONS

CS1602B-D-YSXFDYN-122

V1.1

December16, 2009

Easterntronic LCD Group

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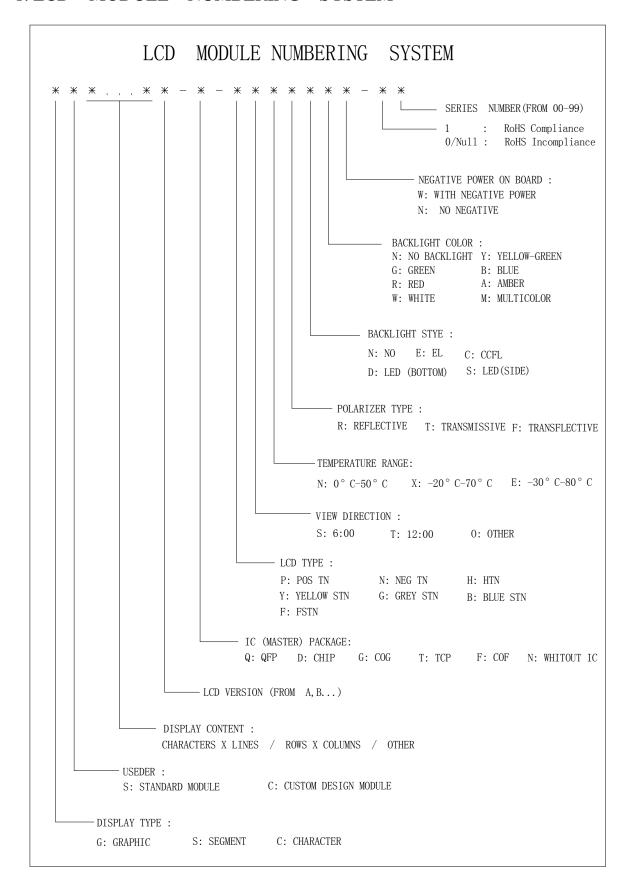
REVISION RECORD

Ver	Description	Page	Date
V1.0 V1.1	First issued Add jumpers connected for drivin A&K,And add quality unites	ng 7,15	Apr 23, 2008 Dec 16 2009

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1. LCD MODULE NUMBERING SYSTEM



2. TYPE NUMBER AND DESCRIPTION

Type Number CS1602B-D-YSXFDYN-122 :

Description 16 Characters X 2 Lines

Yellow-Green STN, Positive, Transflective LCD Panel

1/16 duty and 1/5 bias **Duty and Bias**

Logic Voltage 5.0V

Viewing angle 6H

BackLight Bottom, Yellow-Green LED

Operating Temperature: -20°C--70°C

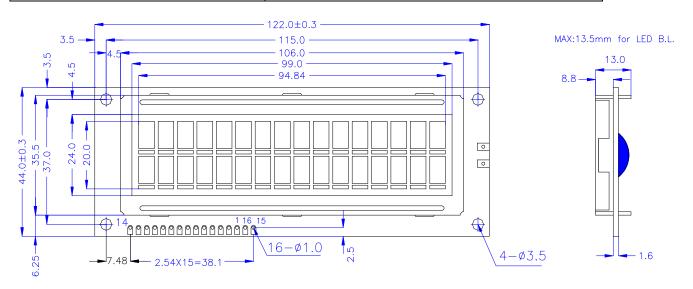
Storage Temperature -30°C --80°C

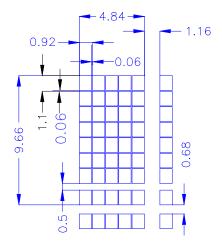
Controller ST7066U-0T or equivalent

Bonding IC package

3. MECHANICAL SPECIFICATIONS:

ITEM	STANDARD VALUE	UNIT
NUMBER OF CHARACTERS	16 CHARACTERS X 2 LINES	
CHARACTER FORMAT	5 X 7 DOTS with CURSOR	
MODULE DIMENSION	122.0(W) X 44.0(H) X 13.0(T)	mm
EFFECTTVE DISPLAY AREA	99.0(W) X 24.0(H)	mm
CHARACTER SIZE	4.84 (W) X 9.66(H)	mm
CHARACTER PITCH	6.0 (W) X 10.34(H)	mm
DOT SIZE	0.92(W) X 1.10(H)	mm
DOT PITCH	0.98(W) X 1.16(H)	mm
APPROX WEIGHT	60	g
LCD TYPE	Yellow-Green STN, Positive, Tra	nsflective
DUTY AND BIAS	1/16 DUTY; 1/5 BIAS	
VIEWING DIRECTION	6:00	
BACK LIGHT	Bottom, Yellow-Green LED	





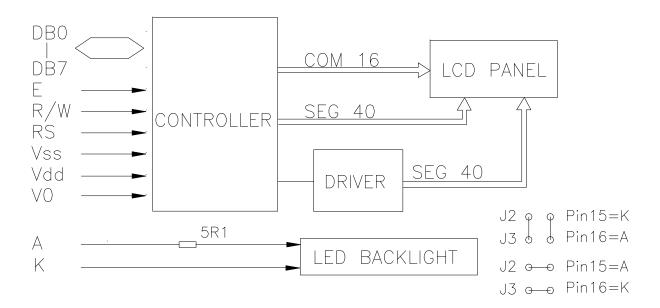
* Remark : Non-specified tolerance refers this model. (± 0.2 mm)

4. ELECTRICAL BLOCK DIAGRAM

4.1 PINS DEFINITION

PIN	SYMBOL	FUNCTION
1	Vss	Power Supply(0V,GND)
2	Vdd	Power Supply for Logic
3	Vo	Contrast Adjust
4	RS	Instruction/Data Register Select
5	R/W	Data Read/Write, L: Write; H: Read
6	Е	Enable Signal
7-14	DB0-DB7	Data Bus Line
15	A	Power Supply for LED Backlight(+)
16	K	Power Supply for LED Backlight(-)

4.2 ELECTRICAL BLOCK DIAGRAM



4.3 DISPLAY CHARACTER ADDRESS CODE

DISPLAY	POSITION																
	ADDRESS	00	01	02	03	04	05	06	07	80	09	ΟA	0B	0C	OD	0E	OF
DUKAM	ADDIVESS	40	41	42	43	44	45	46	47	48	49	4A	4B	4C	4D	4E	4F

5. ABSOLUTE MAXIMUM RATINGS

5.1 Electrical Maximum Ratings (Ta=25deg C)

ITEM	SYMBOL	CONDITI ON	MIN	MAX	UNIT
Supply Voltage (Logic)	Vdd – Vss	-	-0.3	7.0	V
Supply Voltage (LCD Drive)	Vdd – V0	-	VDD-10	VDD+0.3	V
Input Voltage	Vi	-	-0.3	Vdd +0.3	V

5.2 Environmental Conditions

ITEM	SYMBOL	CONDITION	MIN	MAX	UNIT
Operating Temp	Topr	-	0	50	deg C
Storage Temp	Ttsg	-	-10	60	deg C

6. ELECTRICAL SPECIFICATIONS

6.1 Electrical Characteristics at Ta=25 deg C, Vdd = 5.0V + / - 5%

ITEM	SYMBOL	CONDITION	MIN	TY P	MA X	UNI T
Supply Voltage (logic)	Vdd-Vss	-	4.5	5.0	5.5	V
Supply Voltage (LCD)	Vdd-V0	Vdd = 5V	4.2	4.5	4.8	V
Input signal voltage	V-ih	"H" level	0.7VDD	-	Vdd	V
(for E, DB0-7,R/W,RS)	V-il	"L" level	0	-	1	V
Supply Current (logic)	Icc	-	0.9	1.0	1.2	mA
Supply Current (LCD)	Io	-	0.15	0.2	0.27	mA
*Supply Curren(BackLight)	Vled	-	4.0	4.2	4.4	V
*Supply Current (LED)	lf	-	1	240	350	mA
*Peak forward current(B/L)	lfp	I mseo pulse 10% Duty Cycle	-	-	780	mA
*Power dissipation(B/L)	Pd		-	-	1100	mW

^{*}For operation above 25°C, the If \ Ifp&Pd must be derated, the current derating is -6.0 mA/ Blacklight working current must not more than 60% of the Ifmax or Ifpmax according to the working temperature.

6.2 Timing Specifications at Ta = 25 deg C, Vdd = 5.0V + /-10%, Vss = 0V

6.2.1Write mode

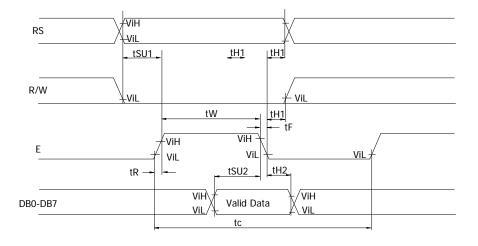
ITEM	SYMBOL	MIN	MAX	UNIT
E cycle time	tc	1200	-	ns
E rise time	tR	-	25	ns
E fall time	tF	-	25	ns
E-pulse width (H, L)	tw	140	-	ns
R/W and RS set-up time	tsul	0	-	ns
R/W and RS hold time	tH1	10	-	ns
Data set-up time	tsu2	40	-	ns
Data hold time	tH2	10	-	ns

6.2.2 Read mode

ITEM	SYMBOL	MIN	MAX	UNIT
E cycle time	tc	1200	-	ns
E rise time	tR	ı	25	ns
E fall time	tF	-	25	ns
E-pulse width (H, L)	tw	140	ı	ns
R/W and RS set-up time	tsu	0	ı	ns
R/W and RS hold time	tH	10	-	ns
Data output delay	tD	ı	100	ns
Data hold time	tDH	10	-	ns

6.2.3 Timing Diagram

Write Mode Timing Diagram



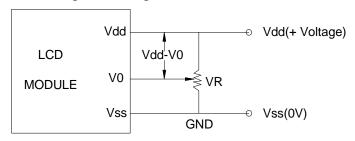
∕ViH RS ViL tH1 _tH_ tSU _ /ViH ViH R/W tW ViH ViH Ε ViL ViL ViL tDH ViH ViH Valid Data DBO-DB7

tc

Read Mode Timing Diagram

7. Example of Power Supply

It is recommended to apply a potentiometer for the contrast adjust due to the tolerance of driving voltage and its temperature dependence.



Vdd - V0: LCD Driving Voltage VR: 10K - 20K

8. ELECTRO-OPTICAL CHARACTERISTIC

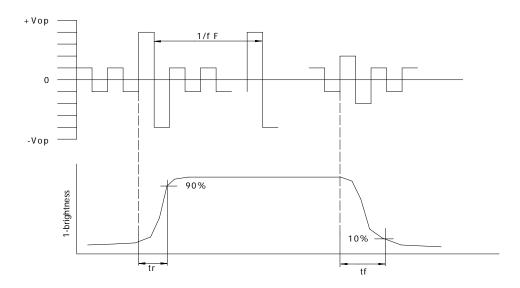
ITEM	SYMB OL	CONDI TION	MIN.	TYP.	MAX.	UNIT	REF.	
Contrast	CR	25℃	1	12	1		Note1	
Rise Time	tr	25℃		160	240	ms	Note2	
Fall Time	tf	25℃		100	150	ms	note 2	
Viewing Angle	θ1-θ2	25℃	i	i	60	DEG	Note 3	
Viewing Angle	Ø1, Ø2	23 C	-40	1	40	DEO	note 3	
Frame Frequency	Ff	25℃		64		Hz	note 2	

Note(1): Contrast ratio is defined under the following condition:

CR= brightness of non-selected condition brightness of selected condition

- (a). Temperature----25C
- (b). Frame Frequency-----64Hz
- (c). Viewing angle----- θ =0, Ø=0
- (d). Operating Voltage---4.5V

Note(2): definition of response time:

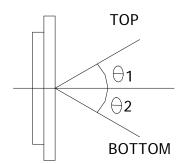


Condition:

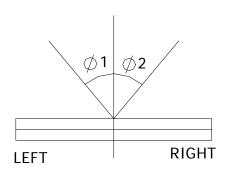
- (a). Temperature-----25C
- (b). Frame Frequency-----64Hz
- (c). Viewing angle----- θ =0, Ø=0
- (d). Operating Voltage---4.5V

Note(3): definition of view angle:

TOP-BOTTOM DIRECTION



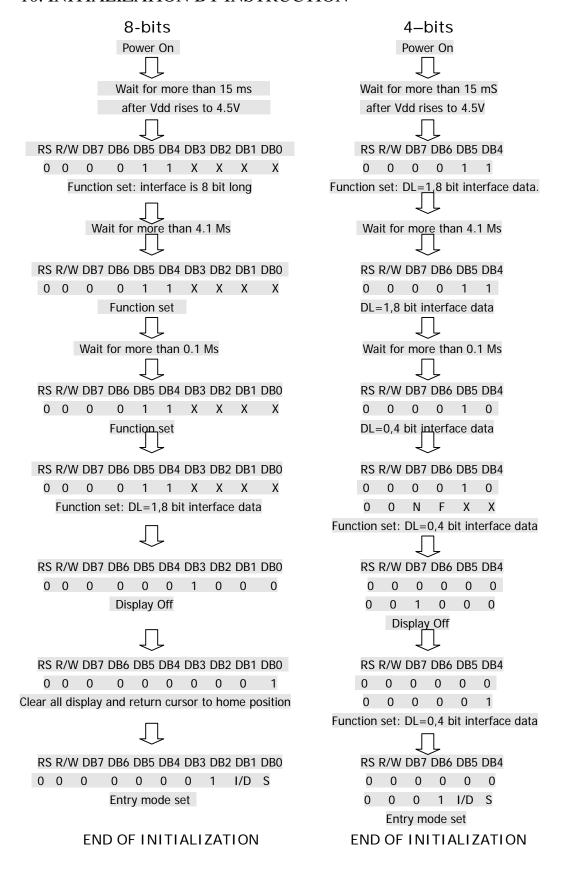
RIGHT-LEFT DIRECTION



9. INSTRUCTION TABLE

Function	R	R	D	D	D	D	D	D	D	D	Description	Execu
	S				В							Time*
		W	7	6	5	4	3	2	1	0		(Max)
Clear	0	0	0	0	0	0	0	0	0	1	Clears entire display and returns the cursor to home	1.64mS
Display											position (address 0)	
Return	0	0	0	0	0	0	0	0	1	X	Return the cursor to the home position. DD RAM	1.64mS
Home											contents remain unchanged. Set DD RAM address to	
											zero.	
Entry	0	0	0	0	0	0	0	1	1	S	Set cursor moving direction and enable the shift of	40μS
mode									/		the display. These operations are performed during	
set									D		data write/read of DD RAM/CG RAM. 1/D=1:	
											increment; 1/D=0: decrement; S=1: whole display	
											shift when data is written.	
Display	0	0	0	0	0	0	1	D	C	В	Set display (D),cursor(C) and blinking of cursor(B)	40μS
ON/OFF											ON/OFF. D=1:display ON; D=0: display OFF.	
control											C=1:Cursor ON; C=0:cursot OFF. B=1:Blink ON;	
											B=0, Blink OFF.	
	0	0	0	0	0	1	S	R	X	X	Move the cursor and shift the display without	
Display							/	/			changing DDRAM contents. S/C=1: Display Shift;	
shift							C	L			S/C=0:Cursor move. R/L=1:shift to right; R/L=0:shift	
											to left.	
Function	0	0	0	0	1	D	N	F	X	X	Set interface data length (DL), number of display lines	40μS
Set						L					(N) and character font (F).DL=1: 8 bits; DL=0: 4 bits.	
											N=1: 2 lines; N=0: 1 lines. F=1: 5X11 dots; F=0:	
											5X7 dots.	
Set CG	0	0	0	1	A	C	G				Set CG RAM address. CG RAM data is sent and	40μS
RAM add											received after this setting.	
Set DD	0	0	1	A	D	D					Set DD RAM address. DD RAM data is sent and	40μS
RAM Add											received after this setting.	
Read BF	0			A	C						Read BUSY FLAG (BF) and the contents of the	0μS
& Addr			F								address counter. BF=1: internal operation; BF=0: can	
											accept instruction.	
Write Data	1	0	W	/R	ΙT	Έ	D	A	ГΑ		Write data into DD RAM or CG RAM.	40
to RAM	L	Ļ		_				_				μS**
Read Data	1	0	R	E	AΓ) I	\mathcal{I}	\T	A		Read data from DD RAM or CG RAM.	40
from RAM												μS**

10. INITIALIZATION BY INSTRUCTION



11. SOFTWARE EXAMPLES

8-BIT OPERATION 16 characters X 1 lines

Function	RS	RW	D7	D6	D5	D4	D3	D2	D1	D0	DISPLAY	DESCRIPTION
Power on delay												Initialization. No display appears.
Function set	0	0	0	0	1	1	0	0	Χ	X		Sets 8-bit operation, 2-line display and 5*7 dots character font.
Display OFF	0	0	0	0	0	0	1	0	0	0		Turn off display.
Display ON	0	0	0	0	0	0	1	1	1	0		Turn on display and cursor.
Entry Mode set	0	0	0	0	0	0	0	1	1	0		Set mode to increment the address by one and to shift the cursor to the right, at the time
												of write to the DD/CG RAM. Display is not shifted.
Write data to CG/DD RAM	1	0	0	1	0	0	1	1	1	1	0	Write "O". Cursor incremented by one and shift to right.
Write data to CG/DD RAM	1	0	0	1	0	1	0	0	1	0	OR	Write "R". Cursor incremented by one and shift to right
Write data to CG/DD RAM											ORIENT	Write "I" "E" "N" "T".
Set DDRAM address	0	0	1	1	0	0	0	0	0	0	ORIENT	Set RAM address so that the cursor is positioned at the 9 th position
Write data to CG/DD RAM					•		•				ORIENT DS	Write "D" "S".
Cursor or display shift	0	0	0	0	0	1	0	0	Х	Х	ORIENT DS	Shift only the cursor position to the left.
Write data to CG/DD RAM											ORIENT DIS	Write "I" "S"

4-bit operation (4-bits 1 line)

Function	RS	RW	/ D7	D6	D5	D4	Display	Description
power on delay								Initialization. No display appears.
Function set	0	0	0	0	1	0		Sets to 4 -bit operation. In this case, operation is handled as 8-bits by initialization, and Only this instruction completes with one write.
Function set	0	0	0	0	1 X	-		Sets 4 -bit operation, 1-line display and 5*7 dot character font. (number of display lines and character fonts cannot be changed hence after.)
Display ON/OFF Control		0	0		0			Turn on display and cursor.
Entry Mode Set	0	0	0	0	0		_	Turn on display and cursor.
Write data to CG/DD/ARM			0 1	1	0	0 1		Write "O". Cursor incremented by one and shift to right.
	same as 8-bit operation							

12.Quality units

12.1 Purpose

This standard for quality assurance should define the quality of LCD module products to customer by EASTERNTIONIC LCD GROUP.

12.2 Scope

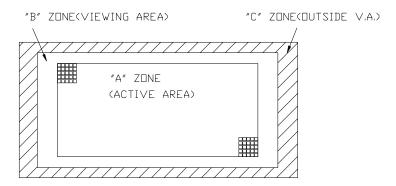
This document defines general provisions as well as inspection standards for LCD module supplied by EASTERNTIONIC LCD GROUP, except for those with special requirements from customer.

12.3 Definition

12.3.1 Definition of area

A Zone: Active area. B Zone: Viewing area

C Zone: Outside viewing area.



12.3.2 Definition of size

Large size(L): $1\sim6$ pcs LCD screens are cut out of from each $14"\times16"$ mother glass. Middle size(M): $7 \sim 50$ pcs LCD screens are cut out of from each $14" \times 16"$ Small size(S): more than 50 pcs LCD screens are cut out of from each 14"×16" glass.

12.4 Quality Specification

12.4.1 Conditions of Cosmetic Inspection

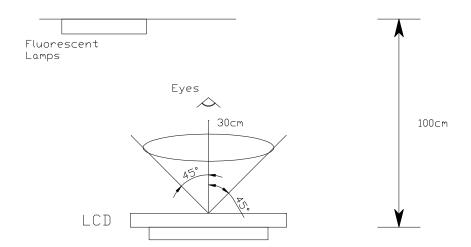
12.4.1 Test should be conducted under the following conditions:

Ambient temperature :22 \pm 5°C. Ambient humidity: $65 \pm 20\%$ RH

Ambient Luminance: 40-watt fluorescent lamp.

An appearance test should be conducted by human sight at approximately 30 cm distance

from the LCD module under fluorescent light. Distance between LCD and fluorescent lamps should be 100 cm or more. Viewing direction for inspection is 45° from vertical against LCD.



12.4.1.2 When test the model of transmissive product must add the reflective plate.

12.4.2 Sampling plan

Unless otherwise agreed in writing, the sampling inspection shall be applied to the incoming inspection of customer.

- Lot size: Quantity of shipment lot per model
- Sampling type: Normal inspection, single sampling
- Sampling Level: Level II
- Sampling table: GB/T2828.1.1(GB-national standard of China)

12.4.3 Classification of defects and Acceptable quality level

Defects and classified as either a major or minor defect defined as bellows:

- Major defect: It is a defect that is likely to result in failure or to reduce materially the usability of the product for the intended function.
- Minor defect: It is a defect that will not result in functioning problem with deviation calssifiec.

The AQL for major and minor defects is defined as follows:

Partition	Definition	AQL
Major defect	Functional defective as product	0.4
Minor defect	Satisfy all functions as product but not satisfy cosmetic standard	1.0

12.4.4 Applicable instrument

- LCD module tester

- Multimeter
- Caliper
- Defect size filming standard

12.4.5 Inspection quality criterion

12.4.5.1 LCD panel part

The inspection specification as following list:

Classify	Item	Description of defects	Inspection criterion		Drawing specification
Major defect				t accept	
	2.LCD with wrong view direction`	Difference in Spec.	No	t accept	
	3.Segment missing	Part or all pattern do not light up	No	t accept	
	4.Occur high current	Current exceed designed value	No	t accept	
	5. LC leakage	LC does not fulfill the glass cell	No	t accept	
	6.Deviation from drawing	LCM Dimension difference from drawing and over tolerance	_	to dimensions be specification	
	7.Wrong type applied	Wrong polarizer attachment	No	t accept	
		Pin attached wrong type applied	No	t accept	
	8.Incorrect pins quality	Pin attached wrong quantity applied	ched Not accept antity		
Minor defect	9.Pattern deformation	Segment fatter or smaller	Dimension (mm) A≤0.1	Acceptable number Not count (Should not be connected to next dot)	

			0.10 <a≤0.15 B≤0.10</a≤0.15 	1 pc / dot(only segment)or less 2 pcs / cell or less (Should not be connected to next dot)	
Minor defect	10.Pinholes	Black spot/white spot at activated state	 large size Accept if c. 1m distance enlarge under 2. Middle size Diameter (mr. Φ≤ 0.15 0.15<Φ≤ 0.25 0.25<Φ≤ 0.35 Φ>0.35 3. Small size Diameter (mr. Φ≤ 0.15 0.15<Φ≤ 0.25 0.25<Φ≤ 0.30 Φ>0.30 4. For the diff the area than or one lattice Only allowed one segments. 	e LCD an't be found at ce and will not er electronic test ize LCD m) Accept QTY Not count 3 1 1 0 0 1 1 1 0 1 1 1 1 0 1 1 1 1 1 1	$\Phi = (X+Y)/2$
	11.Blemishes and foreign matters	Black spot/dust on LCD(non-display)	distance and under electroristic -Middle size	LCD an't find at 1m will not enlarge onic test: LCD m) Accept QTY Not count 3	$\Phi = (X+Y)/2$

$\Phi > 0.35$ 0
-Small size LCD
Diameter(mm) Accept QTY
Φ≤0.15 Not count
$0.15 < \Phi \le 0.25$ 2
$0.25 < \Phi \le 0.30$
$\Phi > 0.30$ 0
2.B zone
1.5 times of acceptable
largest diameter size of Zone
A
3.C zone
Notcount.
Negative panel:
1. A zone
-Large size LCD
Diameter(mm) Accept QTY
Φ ≤ 0.15 Not count
$0.15 < \Phi \le 0.30$ 4
$0.30 < \Phi \le 0.50$
$\Phi > 0.50$ 0
-Middle&small size LCD
Diameter(mm) Accept QTY
$\Phi \le 0.15$ Not count
0.15<Ф≤0.25 3
$\Phi > 0.25$ 0
2. B zone
1.5 times of acceptable
largest diameter size of Zone
A
3.C zone
No count
The nearest diatance allowed
between two black spot is
20mm

12.Black	Scratch on glass	Positive panel:	
lines and	or polarizer	1.A zone	L
scratches	surface.And	- Large size LCD	*
	foreign linear	Accept if can't find at 1m	
	matters in LCD	distance and will not enlarge	
		under electronic test.	
		-Middle size LCD	
		Diameter(mm) Accept QTY	
		$W {\leq} \ 0.02 \qquad \text{Not count}$	
		$0.02 < W \le 0.03, L \le 4 \qquad 2$	
		$0.03 < W \leq 0.05, L \leq 3 \qquad 2$	
		$0.02 < W \le 0.03, L > 4 $ 0	
		$0.03 < W \le 0.05, L > 3 $ 0	
		W>0.05 As the spot criteria.	
		-Small size LCD	
		Diameter(mm) Accept QTY	
		$W \le 0.02$ Not count	
		$0.02 < W \le 0.03, L \le 4$ 2	
		$0.03 < W \le 0.05, L \le 2$	
		$0.02 < W \le 0.03, L > 4$ 0	
		$0.03 < W \le 0.05, L > 2$ 0	
		W>0.05 As the spot criteria.	
		2.B zone	
		1.5 times of acceptable largest	
		diameter size of Zone A	
		3.C zone	
		Notcount.	
		Negative panel:	
		1. A zone -Large size LCD	
		Diameter(mm) Accept QTY	
		$W \le 0.02$ Not count	
		$0.02 < W \le 0.03, L \le 5$ 3	
		$0.03 < W \le 0.05, L \le 4$ 2	
		$0.02 < W \le 0.03, L > 5$ 0	
		$0.03 < W \le 0.05, L > 4 $ 0	
		W>0.05 As the spot criteria.	
		•	

			M: 111 ' T CD	1
			-Middle size LCD	
			Diameter(mm) Accept QTY	
			W≤ 0.02 Not count	
			$0.02 < W \le 0.03, L \le 4$ 2	
			$0.03 < W \le 0.05, L \le 2$ 2	
			$0.02 < W \le 0.03, L > 3$ 0	
			$0.03 < W \le 0.05, L > 2 $ 0	
			W>0.05 As the spot criteria.	
			-Small size LCD	
			Diameter(mm) Accept QTY	
			W≤ 0.02 Not count	
			0.02< W≤ 0.03,L ≤3 2	
			$0.03 < W \le 0.05, L \le 3$	
			$0.02 < W \le 0.03, L > 3$	
			$0.03 < W \le 0.05, L > 2 $ 0	
			W>0.05 As the spot criteria.	
			2. B zone	
			1.5 times of acceptable largest	
			diameter size of Zone A	
			diameter size of Zone A	
			3.C zone	
			Not count	
			The nearest diatance allowed	
			between two defects is 20mm	
Mintor	13. Scratch	PI coating	The visible scratch of A zone can	
defect	on PI coating	scratched	not be accepted at 30cm view	
derect	on i i couning	seratenea	distance.	
Mintor	14. Rainbow	Arches,circular	According to the limit specimen	
defect	1 1. Kaiiioow	or parallel	1 recording to the mint specimen	
acreet		colorful spread		
		coloriul spicad		
Mintor	15. Bubbles	Bubbles or	A zone:The visible defect can	
defect	or wrinkles in	wrinkles	not be accepted at 30cm view	
	polarizer	between	distance.	
	Polarizor	polarizer and	B zone: Not count	
		glass	2 Zone. I tot count	
Mintor	16. Position	Wrong polarizer	Polarizer protruding from edge	
defect	of polarzer	attachment in	of glass and exceeding/within	
derect	attachment	position or	the maximum external	
	attacimicit	dimension	dimension of LCD	
		difficitation	difficultion of LCD	

Mintor defect	17. Ink printing	17.1 Ink line/pattern	Not acce	pt			
	defect	broken 17.2 Ink pattern/line jagged	Accept if the thick or thin part is less than equal to 25% segment width, or according to the limit specimen				
		17.3 Light leakage	white l position due misalign	ectivated ight app of pinho in ment. According to specification			
		17.4 Ink printing pattern/line uneven	than 1/2	the thick own. W. hen W1-V			<u></u> ₩
Mintor defect	18. Pin defect	18.1 Corrosion or foreign material on terminal legs	plating on bott	Pin incoming defect: oxidized,damage(including pins plating damaged),excess epoxy on bottom glass or terminal legs.Not accept.			•
		18.2 Pin deviation over tolerance	Accordin	ng to the s	pecifica	tion	
Mintor defect	19. Chipped glass on	19.1 Chip in lead contact	a	b	c	accept QTY	
	comer	area.	a≤5mm L>5m m	b≤W	c≤T	3	ITO
			a <l L<5m m</l 	b≤W	c≤T	3	IT IT
		19.2 Others	Not exc width of	seed 1/2 seal	c≤T	3	6 - 6 - 0

Mintor	20. Glass	chip on edge	a	b	С	accept QTY	d a
defect		a≤5mm	Not exceed 1/2 width of seal	c≤T	3	, c	
Mintor	21. Clipped electrode pad	21.1Glass chip on ITO edge	a	b	С	accept QTY	ITD
defect			a≤4mm (and not exceed 4 ITO termina 1	b≤W/4	c≤T	3	lo a
		21.2 Glass chip on ITO back	a	b	С	accept QTY	
			a≤5mm	b≤W/3	c≤T	3	N TE
Mintor defect	22. Mechanical	Extended crack inspector shall	b		accept	QTY	0 W
	damage	attempt to remove the chip with tweezers,re-eval uate if the remaining defect is still a crack or a chip	b≤W/4		2		
Mintor defect	23.Gla	Not acce	pt	1			

Remark:

The minimum space between any 2 defects(spot,dirt) should more than 20mm, and max. allowed defect QTY in total:

Large size LCD: Zone A≤ 5/unit, Zone B≤ 5/unit; Middle size LCD: Zone A≤ 3/unit, Zone B≤ 3/unit; Small size LCD: Zone A≤ 2/unit, Zone B≤ 2/unit;

12.4.5.2 Other part

The inspection specification as following list:

NO.	Items	Criterion of defects	AQL
1	Backlight	 Lumination source flickers. Using spot, lines and contamination standard of LCD to judge the spots or scratches defect on backlight. 	Major Minor
		3. Not allow unlighted on backlight.	Major
		4. Colour and luminance of backlight should correspond its	Major
		specification.	iviajoi
2	PCB,COB	1.COB seal may not have pinholes larger than 0.2mm or contamination.	Mino
		2.COB seal surface may not have pinholes through to the IC.	Mino
		3. The height of COB should not exceed the height indicated in the assembly diagram.	Major
		4. Beyond 2mm of the seal area, there may not have sealant on the PCB.	Mino
		5.No oxidation or contamination on PCB connector.	Mino
		6.Parts on PCB should correspond the characteristic, and not	Major
		allow wrong parts, missing parts or additional parts.	
		7. The jumper on the PCB should correspond to the	Mino
		characteristic.	
		8.The solder which gets on bezel,LED pad,zebra pad or	Major
		screw hole pad should be smoothed down.	
2	0.11 '	1. No unmelted solder pastes on the PCB.	Mino
3	Soldering	2. No cold solder joints, solder connection missing, oxidation of solder.	Mino
		3. No short circuits in components on PCB.	Mino
4	General Appearance	1. No oxidation, contamination, curves, cracks or bends on interface Pin of TCP.	Mino
		2. No solder residue or solder balls on product.	Mino
		3. The IC on TCP may not be damaged.	Majo
		4. The residual rosin or tin oil of soldering(component or chip component) is not turned into brown or black colour.	Mino
		5. Packing method correspond the specification.	Major
		6. Dimension and structure correspond the specification sheet.	Majo
		7. No dirt and break on the heat seal.	Majo

12.5 Reliability

The LCD module shall not fail the following reliability test.

Item	Condition	Criterion			
High temperature	+70°C ±2°C, 8 hc				
operation					
Low temperature	$-20^{\circ}\text{C} \pm 2^{\circ}\text{C}$, 8 ho	urs	1.Total current		
operation			consumption		
Humidity	Operation	$40^{\circ}\text{C} \pm 2^{\circ}\text{C}$,93% $\pm 2\%$ RH,8	should be below		
		hours	double of initial		
	Storage	$40 ^{\circ}\text{C} \pm 2 ^{\circ}\text{C},93\% \pm 2\%\text{RH},$	value.		
	C	24 hours	2.Cosmetic defects		
High temperature	+80°C ±2°C, 10 h	ours	should not be		
storage			happened		
Low temperature	-30°C ±2°C, 10 he	ours			
storage					
Thermal shock	-20°C∼+70°C				
storage	60min~60min, 5 cy	vcles			
Vibration test	Amplitude:0.7~1.0	mm,frequency:50Hz,30min			
	in each direction(X				
Shock test		er dropping from 60cm or			
	80cm high on the c	oncrete surface in packing			
	state.(weight≥15K	Ag,dropping height 60cm;			
	Weight<15Kg,dro	pping height 80cm)			
		Duamina mathad			
	F	Dropping method corner dropping			
	E	D A corner: once			
	G				
	В				
	60/8				
	†				
		Concrete Surface			

Remark: The function test shall be conducted after 4 hours storage at the normal temperature and humidity after removed from the test chamber.

13. Character Pattern

67-64 63-60	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	1111
0000	CG RAM (1)															
0001	(2)															
0010	(3)															
0011	(4)															
0100	(5)															
0101	(6)															
0110	(7)		*													
0111	(8)															
1000	(1)															
1001	(2)															
1010	(3)															
1011	(4)															
1100	(5)															
1101	(6)															
1110	(7)															
1111	(8)															

14. PRECAUTION FOR USING LCM

1. LIQUID CRYSTAL DISPLAY (LCD)

LCD is made up of glass, organic sealant, organic fluid, and polymer based polarizers. The following precautions should be taken when handing,

- (1). Keep the temperature within range of use and storage. Excessive temperature and humidity could cause polarization degredation, polarizer peel off or bubble.
- (2). Do not contact the exposed polarizers with anything harder than an HB pencil lead. To clean dust off the display surface. Wipe gently with cotton. Chamois or other soft material soaked in petroleum benzin.
- (3). Wipe off saliva or water drops immediately. Contact with water over a long period of time may cause polarizer deformation or color fading, while an active LCD with water condensation on its surface will cause corrosion of ITO electrodes.
- (4). Glass can be easily chipped or cracked from rough handing. especially at corners and edges.
- (5). Do not drive LCD with DC voltage.

2. Liquid Crystal Display Modules

2.1 Mechanical Considerations

LCM are assembled and adjusted with a high degree of precision. Avoid excessive shocks and do not make any alterations or modifications. The following should be noted.

- (1). Do not tamper in any way with the tabs on the tabs on the metal frame.
- (2). Do not modify the PCB by drilling extra holes, changing its outline, moving its components or modifying its pattem.
- (3). Do not touch the elastomer connector, especially insert an backlight panel (for example, EL).
- (4). When mounting a LCM make sure that the PCB is not under any tress such as bending or twisting. Elastomer contacts are very delicate and missing pixels could result from slight dislocation of any of the elements.
- (5). Avoid pressing on the metal bezel, otherwise the elastomer connector could be deformed and lose contact, resulting in missing pixels.

2.2. Static Electricity

LCM contains CMOS LSI's and the same precaution for such devices should apply, namely

- (1). The operator should be grounded whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.
- (2). The modules should be kept in antistatic bags or other containers resistant to static for storage.
- (3). Only properly grounded soldering irons should

be used.

- (4). If an electric screwdriver is used, it should be well grounded and shielded from commutator sparks.
- (5). The normal static prevention measures should be observed for work clothes and working benches; for the latter conductive (rubber) mat is recommended.
- (6). Since dry air is inductive to statics, a relative humidity of 50-60% is recommended.
- 2.3. Soldering
- (1). Solder only to the I/O terminals.
- (2). Use only soldering irons with proper grounding and no leakage.
- (3). Soldering temperature: 280 $^{\circ}\text{C} \pm 10^{\circ}\text{C}$
- (4). Soldering time: 3 to 4 sec.
- (5). Use eutectic solder with resin flux fill.
- (6). If flux is used, the LCD surface should be covered to avoid flux spatters. Flux residue should be removed after wards.

2.4. Operation

- (1). The viewing angle can be adjusted by varying the LCD driving voltage V0.
- (2). Driving voltage should be kept within specified range; excess voltage shortens display life.
- (3). Response time increases with decrease in temperature.
- (4). Display may turn black or dark blue at temperatures above its operational range; this is (however not pressing on the viewing area) may cause the segments to appear "fractured".
- (5). Mechanical disturbance during operation (such as pressing on the viewing area) nay cause the segments to appear "fractured".

2.5. Storage

If any fluid leaks out of a damaged glass cell, wash off any human part that comes into contact with soap and water. Never swallow the fluid. The toxicity is extremely low but caution should be exercised at all the time.

2.6. Limited Warranty

Unless otherwise agreed between ORIENT DISPLAY and customer, ORIENT DISPLAY will replace or repair any of its LCD and LC, which is found to be defective electrically and visually when inspected in accordance with ORIENT DISPLAY acceptance standards, for a period on one year from data of shipment. Confirmation of such date shall be based on freight documents. The warranty liability of ORIENT DISPLAY is limited to repair and/or replacement on the terms set forth above. ORIENT DISPLAY will not responsible for any subsequent or consequential events.

15. Declaration of conformity regarding the limitation of dangerous substances

深圳易事通液晶显示模块有限公司

SHENZHEN EASTERNTRONIC LCM CO., LTD.

4F, B3 Building, FuYuan Industrial Zone, FuYong Town,

BaoAn District, ShenZhen, P.R.China

DECLARATION OF CONFORMITY REGARDING THE LIMITATION OF DANGEROUS SUBSTANCES.

WE, SHENZHEN EASTERNTRONIC LCM CO., LTD,

Declare that the product of CS1602B-D-YSXFDYN-122 complies with: The directive 2002/95/EC Dated 2003/01/27 regarding the limitation of dangerous substances, in particular to clause 4 which forbids the use of the following elements:

- Lead
- Mercury
- Cadmium
- Hexavalant chromium
- •Polybrominated biphenyls
- ●Polybrominated diphenylethers

And to the annex which points out the exempted implementations \square To the directive 73/23/eec dated 1973/02/19 and the standard EN60335-1 regarding prohibition of following elements:

- Oils containing polychlorinated biphenyl
- Asbestos
- Radioactive substances

Name: DING

SHENZHEN EASTERNTRONIC LCM CO., LTD.

Issued on December 16, 2009

According with the proposal of Technical Adaption Committee (TAC) of a limit of 0.1% by weight for lead hexavalent chromium, mercury, PBBs and PBDRs and 0.01% by weight for Cadmium.